

## MSHM30P32

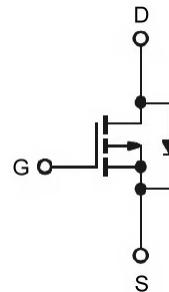
### P-Channel 30-V (D-S) MOSFET

#### Description

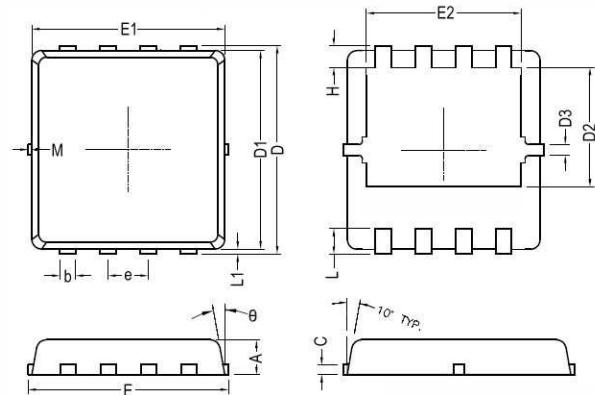
The device is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The device meets the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Graphic Symbol

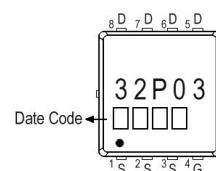


#### Package Dimension



REF.	Millimeter			REF.	Millimeter		
	Min.	Nom.	Max.		Min.	Nom.	Max.
A	0.70	0.75	0.80	E1	3.00	3.15	3.20
b	0.25	0.30	0.35	E2	2.39	2.49	2.59
C	0.10	0.15	0.25	e	0.65 BSC		
D	3.25	3.35	3.45	H	0.30	0.39	0.50
D1	3.00	3.10	3.20	L	0.30	0.40	0.50
D2	1.78	1.88	1.98	L1	-	0.13	0.20
D3	-	0.13	-	theta	-	10°	12°
E	3.20	3.30	3.40	M	-	-	0.15

#### Marking



RoHS Compliant

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#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings			
Symbol	Parameter	Value	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>1</sup> ( $T_C = 25^\circ\text{C}$ )	-32	A
	Continuous Drain Current <sup>1</sup> ( $T_C = 100^\circ\text{C}$ )	-20	A
$I_{DM}$	Pulsed Drain Current <sup>1,2</sup>	-65	A
$I_{AS}$	Single Pulse Avalanche Current, $L = 0.1\text{mH}^3$	-38	A
$E_{AS}$	Single Pulse Avalanche Energy, $L = 0.1\text{mH}^3$	72.2	mJ
$P_D$	Power Dissipation <sup>4</sup> ( $T_C = 25^\circ\text{C}$ )	29	W
	Power Dissipation <sup>4</sup> ( $T_A = 25^\circ\text{C}$ )	1.67	W
$T_J/T_{STG}$	Operating Junction and Storage Temperature	-55 to +150	°C

Thermal Resistance Ratings			
Symbol	Parameter	Maximum	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient <sup>1</sup>	75	°C/W
$R_{\theta JC}$	Maximum Junction-to-Case <sup>1</sup>	4.3	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-1.0	-	-2.5	V
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	-	-	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-15\text{A}$	-	19	-	S
$I_{GSS}$	Gate-Source Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$ $V_{DS}=-24\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	-	-	-1 -5	$\mu\text{A}$
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-15\text{A}$	-	18	20	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-10\text{A}$	-	27	32	
$EAS$	Single Pulse Avalanche Energy <sup>5</sup>	$V_{DD}=-25\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=-20\text{A}$	20	-	-	mJ
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$I_S=-15\text{A}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	-	-	-1.2	V
$I_S$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	-	-	-32	A
$I_{SM}$	Pulsed Source Current <sup>2,6</sup>		-	-	-65	

#### Notes

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
3. The EAS data shows maximum rating. The test condition is  $V_{DD}=-25\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-38\text{A}$ .
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.
5. The Min. value is 100% EAS tested guarantee.
6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

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Dynamic						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	V <sub>DS</sub> = -15V I <sub>D</sub> = -15A V <sub>GS</sub> = -4.5V	--	12.5	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	5.4	--	
Q <sub>gd</sub>	Gate-Drain Charge		--	5	--	
t <sub>d(on)</sub>	Turn-On Delay Time <sup>2</sup>	V <sub>DS</sub> = -15V I <sub>D</sub> = -15A V <sub>GS</sub> = -10V R <sub>G</sub> = 3.3Ω	--	4.4	--	ns
t <sub>r</sub>	Rise Time		--	11.2	--	
t <sub>d(off)</sub>	Turn-Off Delay Time		--	34	--	
t <sub>f</sub>	Fall Time		--	18	--	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V V <sub>GS</sub> = 0V f = 1.0MHz	--	1345	--	pF
C <sub>oss</sub>	Output Capacitance		--	194	--	
C <sub>RSS</sub>	Reverse Transfer Capacitance		--	158	--	
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> = V <sub>DS</sub> = 0V, f = 1.0MHz	--	13	--	Ω

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### P-Channel 30-V (D-S) MOSFET

- Typical Electrical Characteristics

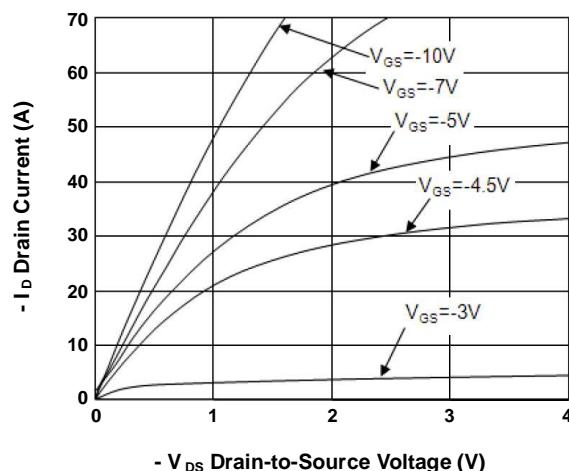


FIG.1-Typical Output Characteristics

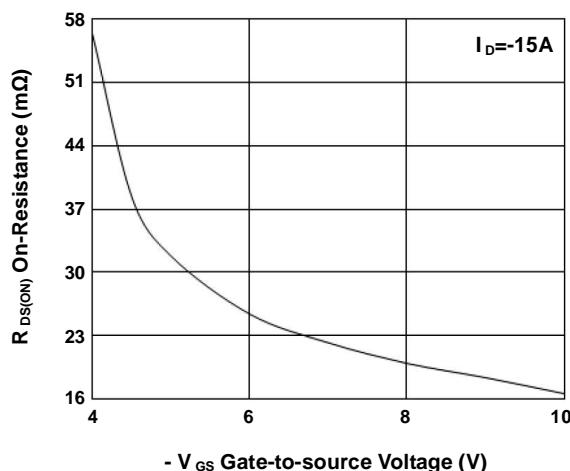


FIG.2-On-Resistance vs. G-S Voltage

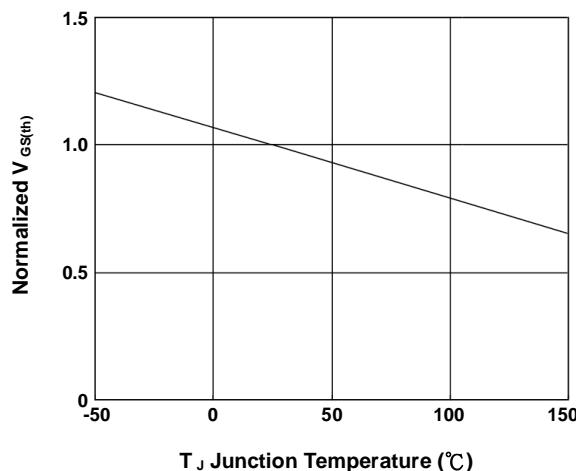


FIG.3-Normalized  $V_{GS(th)}$  vs.  $T_J$

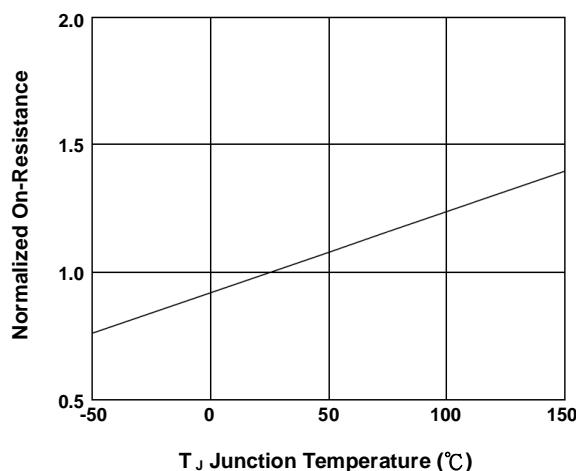


FIG.4-Normalized  $R_{DS(on)}$  vs.  $T_J$

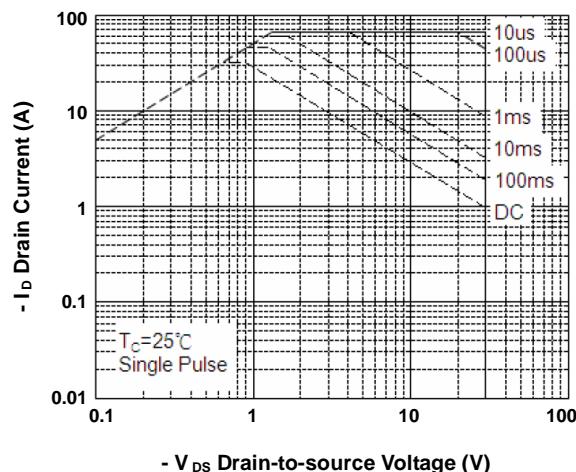


FIG.5-Safe Operating Area

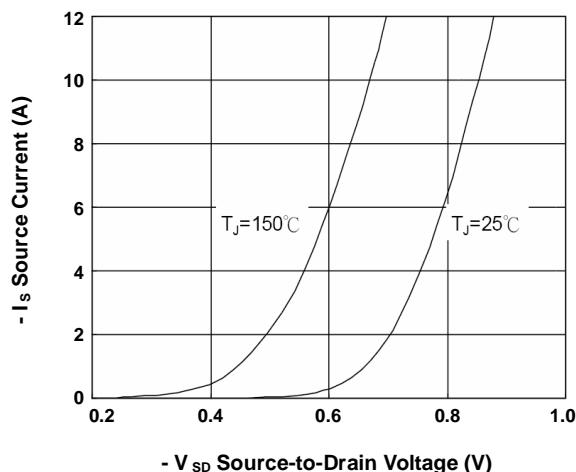


FIG.6-Forward Characteristics of Reverse

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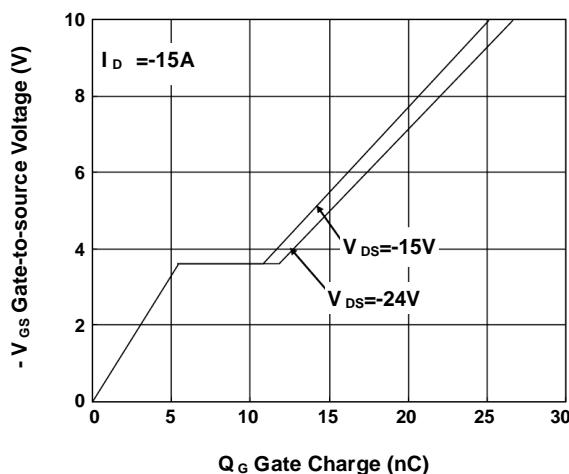


FIG.7-Gate Charge Characteristics

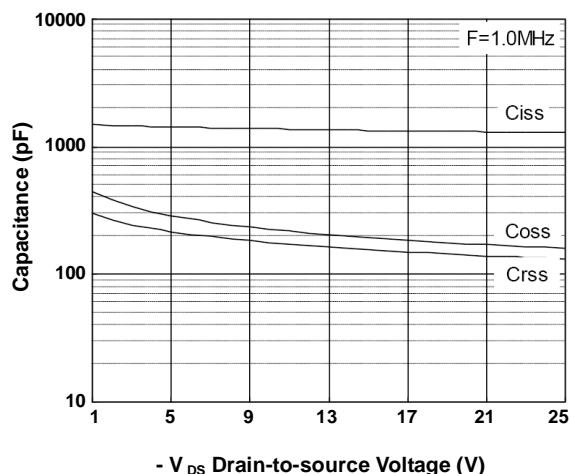


FIG.8-Capacitance Characteristics

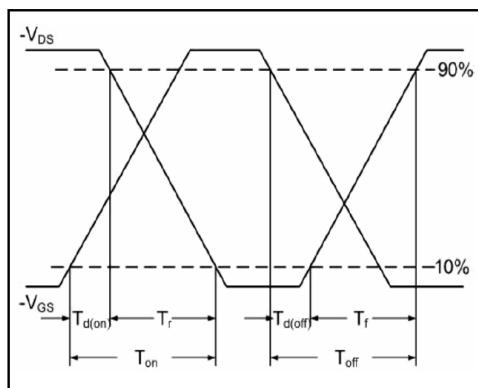


FIG.9-Switching Time Waveform

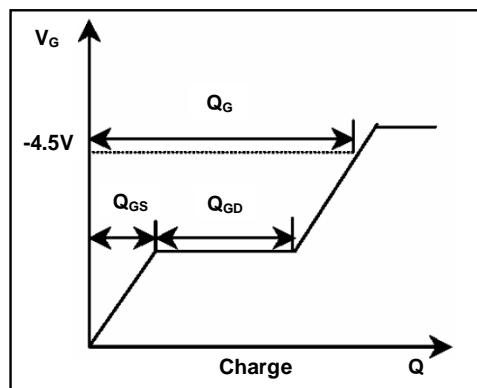


FIG.10-Gate Charge Waveform

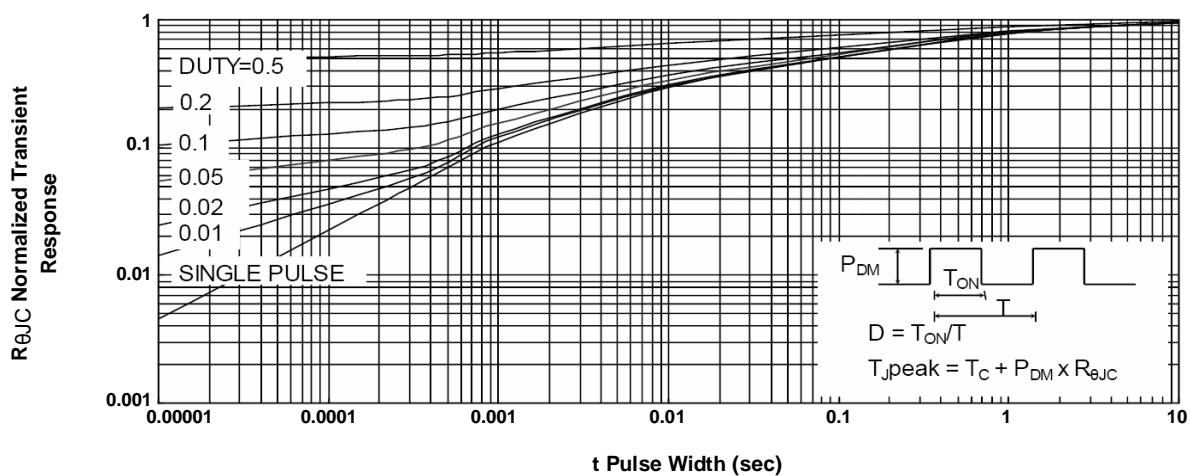


FIG.11-Normalized Maximum Transient Thermal Impedance

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